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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10010169	FILING DATE 11/13/2001	CLASS 360	SUBCLASS 234.5	GAU 2652	EXAMINER 11-11
**APPLICANTS: Segar Richard; Ramdular Juma; Gallup Paul; Rice John; Larson Richard; Gronseth Michael; Jones Gordon; 2652					
**CONTINUING DATA VERIFIED: THIS APPLN CLAIMS BENEFIT OF 60/249,081 11/15/2000					
** FOREIGN APPLICATIONS VERIFIED:					
PG PUB DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input checked="" type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials <i>Dr</i>				169.12-0502	
TITLE : HGA ballbond assembly with wafer process assembly features					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL		Application Examiner	
DISCLAIMER		PREPARED FOR ISSUE	
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